

## CMOS Decade Counters/Dividers

High-Voltage Types (20-Volt Rating)

With Decoded 7-Segment Display Outputs and:

Display Enable – CD4026B

Ripple Blanking – CD4033B

■ CD4026B and CD4033B each consist of a 5-stage Johnson decade counter and an output decoder which converts the Johnson code to a 7-segment decoded output for driving one stage in a numerical display.

These devices are particularly advantageous in display applications where low power dissipation and/or low package count are important.

Inputs common to both types are CLOCK, RESET, & CLOCK INHIBIT; common outputs are CARRY OUT and the seven decoded outputs (a, b, c, d, e, f, g). Additional inputs and outputs for the CD4026B include DISPLAY ENABLE input and DISPLAY ENABLE and UNGATED "C-SEGMENT" outputs. Signals peculiar to the CD4033B are RIPPLE-BLANKING INPUT AND LAMP TEST INPUT and a RIPPLE-BLANKING OUTPUT.

A high RESET signal clears the decade counter to its zero count. The counter is advanced one count at the positive clock signal transition if the CLOCK INHIBIT signal is low. Counter advancement via the clock line is inhibited when the CLOCK INHIBIT signal is high. The CLOCK INHIBIT signal can be used as a negative-edge clock if the clock line is held high. Antilock gating is provided on the JOHNSON counter, thus assuring proper counting sequence. The CARRY-OUT ( $C_{out}$ ) signal completes one cycle every ten CLOCK INPUT cycles and is used to clock the succeeding decade directly in a multi-decade counting chain.

The seven decoded outputs (a, b, c, d, e, f, g) illuminate the proper segments in a seven

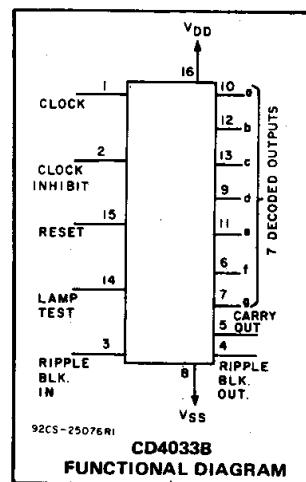
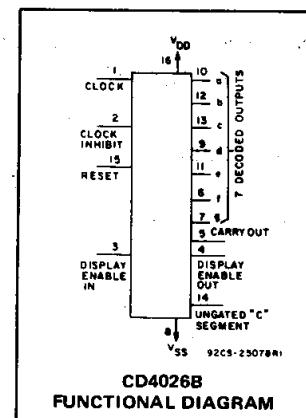
### Features:

- Counter and 7-segment decoding in one package
- Easily interfaced with 7-segment display types
- Fully static counter operation: DC to 6 MHz (typ.) at  $V_{DD}=10$  V
- Ideal for low-power displays
- Display enable output (CD4026B)
- "Ripple blanking" and lamp test (CD4033B)
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Schmitt-triggered clock inputs
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

### Applications

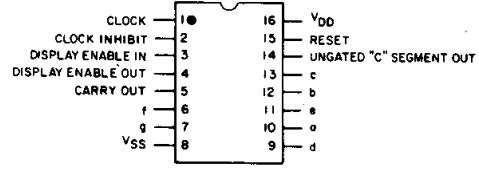
- Decade counting 7-segment decimal display
- Frequency division 7-segment decimal displays
- Clocks, watches, timers (e.g.  $\div 60$ ,  $\div 60$ ,  $\div 12$  counter/display)
- Counter/display driver for meter applications

segment display device used for representing the decimal numbers 0 to 9. The 7-segment outputs go high on selection in the CD4033B; in the CD4026B these outputs go high only when the DISPLAY ENABLE IN is high.

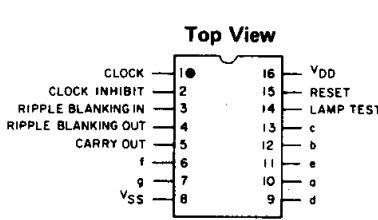


### TERMINAL DIAGRAMS

#### Top View



#### Top View



### MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )

Voltages referenced to  $V_{SS}$  Terminal) ..... -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS

-0.5V to  $V_{DD}$  +0.5V

DC INPUT CURRENT, ANY ONE INPUT

$\pm 10$ mA

POWER DISSIPATION PER PACKAGE ( $P_D$ ):

For  $T_A = -55^\circ\text{C}$  to  $+100^\circ\text{C}$  ..... 500mW

For  $T_A = +100^\circ\text{C}$  to  $+125^\circ\text{C}$  ..... Derate Linearity at 12mW/ $^\circ\text{C}$  to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR  $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$  ..... 100mW

OPERATING-TEMPERATURE RANGE ( $T_A$ ) ..... -55 $^\circ\text{C}$  to +125 $^\circ\text{C}$

STORAGE TEMPERATURE RANGE ( $T_{stg}$ ) ..... -65 $^\circ\text{C}$  to +150 $^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING):

At distance  $1/16 \pm 1/32$  inch (1.59  $\pm$  0.79mm) from case for 10s max ..... +265 $^\circ\text{C}$

At distance  $1/16 \pm 1/32$  inch (1.59  $\pm$  0.79mm) from case for 10s max ..... +265 $^\circ\text{C}$

## CD4026B, CD4033B Types

### RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V <sub>DD</sub> (V)	LIMITS		UNITS	
		MIN.	MAX.		
Supply-Voltage Range (For T <sub>A</sub> = Full Package Temperature Range)		3	18	V	
Clock Input Frequency, f <sub>CL</sub>	5	—	2.5	MHz	
	10	—	5.5		
	15	—	8		
Clock Pulse Width, t <sub>WCL</sub>	5	220	—	ns	
	10	100	—		
	15	80	—		
Clock Rise and Fall Time, t <sub>CL</sub> -t <sub>fCL</sub>	5	—	Unlimited		
	10	—			
	15	—			
Clock Inhibit Set Up Time, t <sub>SU</sub>	5	200	—		
	10	50	—		
	15	30	—		
Reset Pulse Width, t <sub>R</sub>	5	200	—		
	10	100	—		
	15	50	—		
Reset Removal Time	5	30	—		
	10	15	—		
	15	10	—		

### STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS	
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	+25								
				-55	-40	+85	+125	Min.	Typ.	Max.		
Quiescent Device Current, I <sub>DD</sub> Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA	
	—	0,10	10	10	10	300	300	—	0.04	10		
	—	0,15	15	20	20	600	600	—	0.04	20		
	—	0,20	20	100	100	3000	3000	—	0.08	100		
Output Low (Sink) Current I <sub>OL</sub> Min.	0,4	0,5	5	0,64	0,61	0,42	0,36	0,51	1	—	mA	
	0,5	0,10	10	1,6	1,5	1,1	0,9	1,3	2,6	—		
	1,5	0,15	15	4,2	4	2,8	2,4	3,4	6,8	—		
Output High (Source) Current, I <sub>OH</sub> Min.	4,6	0,5	5	-0,64	-0,61	-0,42	-0,36	-0,51	-1	—	mA	
	2,5	0,5	5	-2	-1,8	-1,3	-1,15	-1,6	-3,2	—		
	9,5	0,10	10	-1,6	-1,5	-1,1	-0,9	-1,3	-2,6	—		
	13,5	0,15	15	-4,2	-4	-2,8	-2,4	-3,4	-6,8	—		
Output Voltage: Low-Level, V <sub>OL</sub> Max.	—	0,5	5	0,05				—	0	0,05	V	
	—	0,10	10	0,05				—	0	0,05		
	—	0,15	15	0,05				—	0	0,05		
Output Voltage: High-Level, V <sub>OH</sub> Min.	—	0,5	5	4,95				4,95	5	—	V	
	—	0,10	10	9,95				9,95	10	—		
	—	0,15	15	14,95				14,95	15	—		
Input Low Voltage, V <sub>IL</sub> Max.	0,5, 4,5	—	5	1,5				—	—	1,5	V	
	1,9	—	10	3				—	—	3		
	1,5, 13,5	—	15	4				—	—	4		
Input High Voltage, V <sub>IH</sub> Min.	0,5, 4,5	—	5	3,5				3,5	—	—	V	
	1,9	—	10	7				7	—	—		
	1,5, 13,5	—	15	11				11	—	—		
Input Current I <sub>IN</sub> Max.	—	0,18	18	±0,1	±0,1	±1	±1	—	±10 <sup>-5</sup>	±0,1	μA	

### CD4026B

When the DISPLAY ENABLE IN is low the seven decoded outputs are forced low regardless of the state of the counter. Activation of the display only when required results in significant power savings. This system also facilitates implementation of display-character multiplexing.

The CARRY OUT and UNGATED "C-SEGMENT" signals are not gated by the DISPLAY ENABLE and therefore are available continuously. This feature is a requirement in implementation of certain divider functions such as divide-by-60 and divide-by-12.

### CD4033B

The CD4033B has provisions for automatic blanking of the non-significant zeros in a multi-digit decimal number which results in an easily readable display consistent with normal writing practice. For example, the number 0050.0700 in an eight digit display would be displayed as 50.07. Zero suppression on the integer side is obtained by connecting the RBI terminal of the CD4033B associated with the most significant digit in the display to a low-level voltage and connecting the RBO terminal of that stage to the RBI terminal of the CD4033B in the next-lower significant position in the display. This procedure is continued for each succeeding CD4033B on the integer side of the display.

On the fraction side of the display the RBI of the CD4033B associated with the least significant bit is connected to a low-level voltage and the RBO of that CD4033B is connected to the RBI terminal of the CD4033B in the next more-significant-bit position. Again, this procedure is continued for all CD4033B's on the fraction side of the display.

In a purely fractional number the zero immediately preceding the decimal point can be displayed by connecting the RBI of that stage to a high level voltage (instead of to the RBO of the next more-significant-stage). For example: optional zero → 0.7346. Likewise, the zero in a number such as 763.0 can be displayed by connecting the RBI of the CD4033B associated with it to a high-level voltage.

Ripple blanking of non-significant zeros provides an appreciable savings in display power.

The CD4033B has a LAMP TEST input which, when connected to a high-level voltage, overrides normal decoder operation and enables a check to be made on possible display malfunctions by putting the seven outputs in the high state.

The CD4026B- and CD4033B-series types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

## CD4026B, CD4033B Types

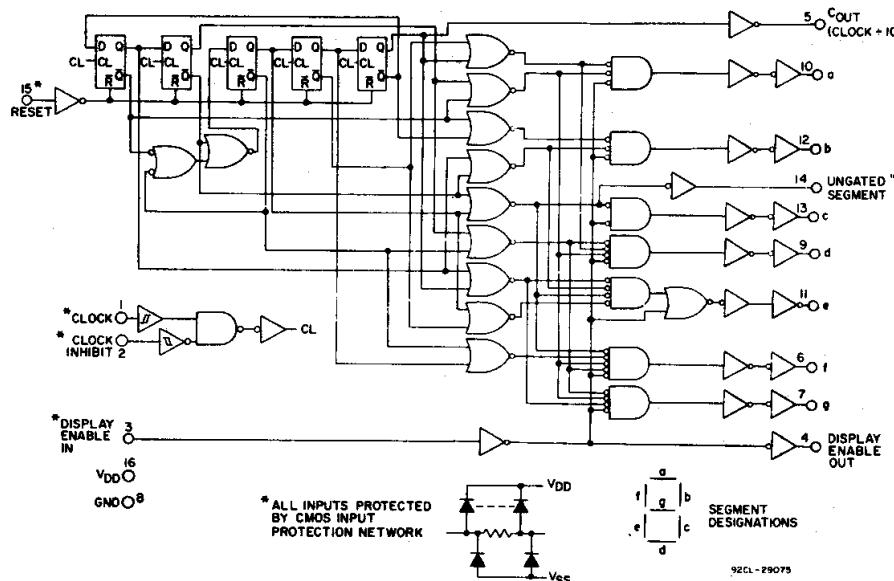


Fig. 1 – CD4026B logic diagram.

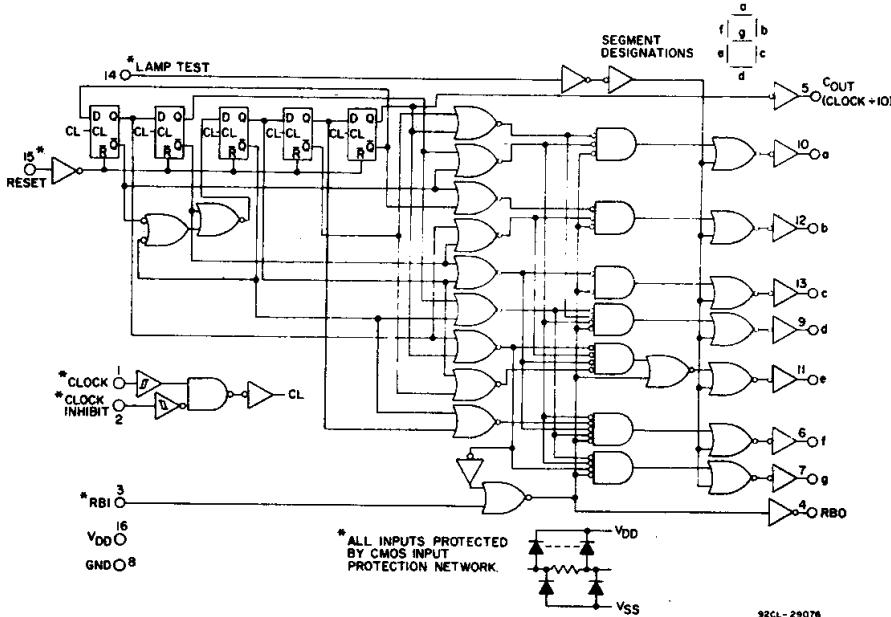


Fig. 2 – CD4033B logic diagram.

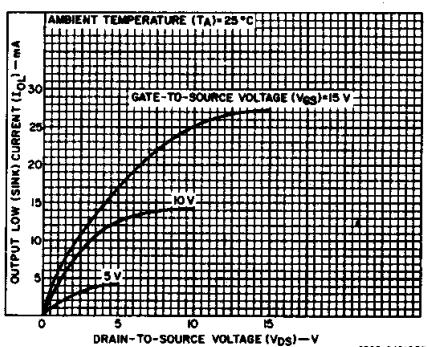


Fig. 6 – Typical n-channel output low (sink) current characteristics.

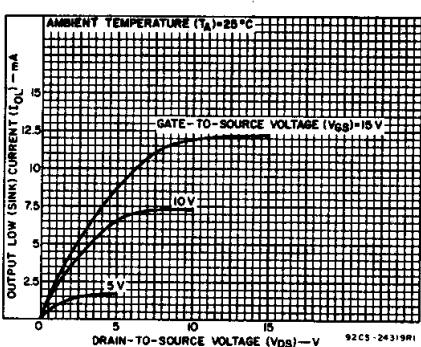


Fig. 7 – Minimum n-channel output low (sink) current characteristics.

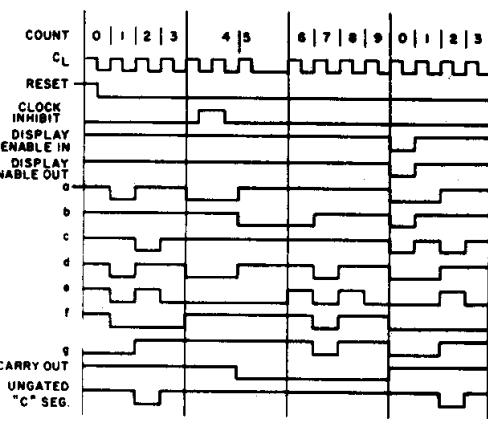


Fig. 3 – CD4026B timing diagram.

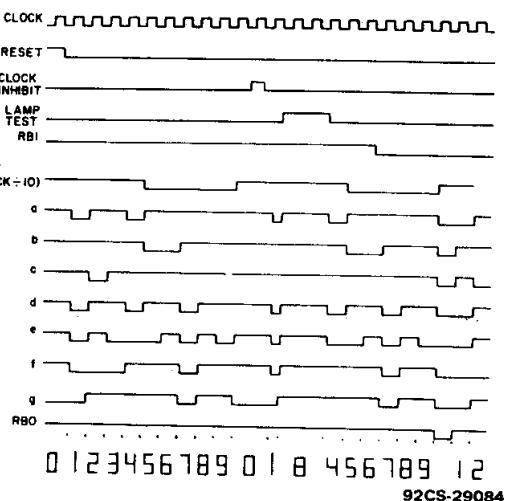


Fig. 4 – CD4033B timing diagram.

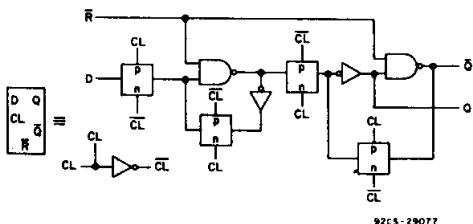


Fig. 5 – Detail of typical flip-flop stage for both types.

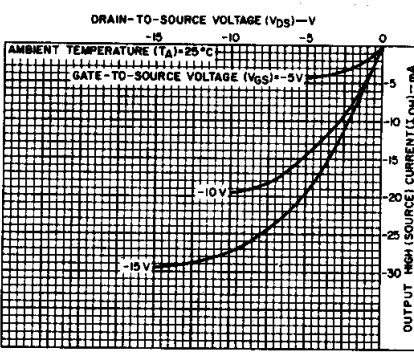


Fig. 8 – Typical p-channel output high (source) current characteristics.

# CD4026B, CD4033B Types

**DYNAMIC ELECTRICAL CHARACTERISTICS** at  $T_A = 25^\circ\text{C}$ , Input  $t_r, t_f = 20\text{ ns}$ ,  
 $C_L = 50\text{ pF}, R_L = 200\text{ k}\Omega$

CHARACTERISTIC	TEST CONDITIONS $V_{DD}$ (V)	LIMITS			UNITS
		Min.	Typ.	Max.	
<b>CLOCKED OPERATION</b>					
Propagation Delay Time; $t_{PLH}, t_{PHL}$ Carry-Out Line		5	—	250 500	ns
		10	—	100 200	
		15	—	75 150	
Decode Outlines		5	—	350 700	
		10	—	125 250	
		15	—	90 180	
Transition Time; $t_{THL}, t_{TLH}$ Carry-Out Line		5	—	100 200	MHz
		10	—	50 100	
		15	—	25 50	
Maximum Clock Input Frequency, $f_{CL}^\Delta$		5	2.5	5 —	
		10	5.5	11 —	
		15	8	16 —	
Min. Clock Pulse Width, $t_W$		5	—	110 220	
		10	—	50 100	
		15	—	40 80	
Clock and Clock Inhibit Rise or Fall Time; $t_{rCL}, t_{fCL}$		5	Unlimited		ns
		10			
		15			
Average Input Capacitance, $C_{IN}$	Any Input	—	5	7	pF
<b>RESET OPERATION</b>					
Propagation Delay Time; To Carry-Out Line, $t_{PLH}$		5	—	275 550	ns
		10	—	120 240	
		15	—	80 160	
To Decode Out Lines, $t_{PHL}, t_{PLH}$		5	—	300 600	
		10	—	125 250	
		15	—	90 180	
Min. Reset Pulse Width, $t_W$		5	—	100 120	
		10	—	50 100	
		15	—	25 50	
Min. Reset Removal Time		5	—	0 30	
		10	—	0 15	
		15	—	0 10	

<sup>Δ</sup> Measured with respect to carry-out line.

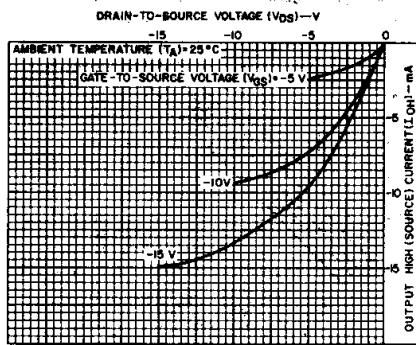


Fig. 9 – Minimum p-channel output high (source) current characteristics.

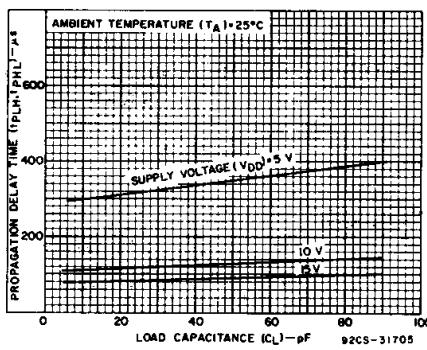


Fig. 10 – Typical propagation delay time as a function of load capacitance for decoded outputs.

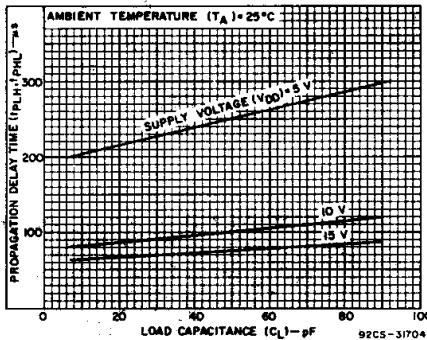


Fig. 11 – Typical propagation delay time as a function of load capacitance for carry-out outputs.

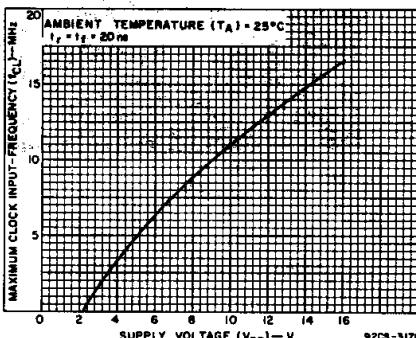


Fig. 12 – Typical maximum clock input-frequency as a function of supply voltage.

## CD4026B, CD4033B Types

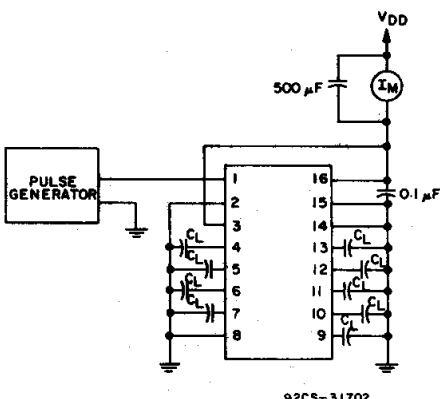
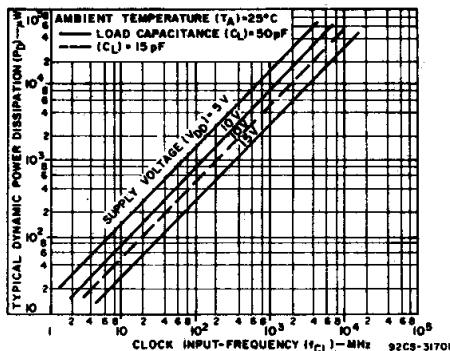


Fig. 14 – Dynamic power dissipation test circuit for CD4033B.

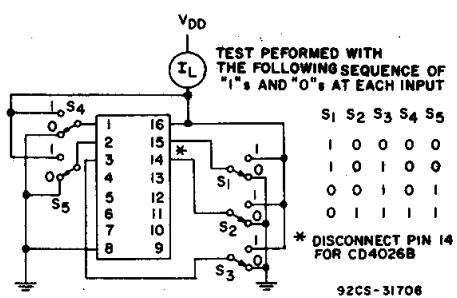


Fig. 15 – Quiescent device current.

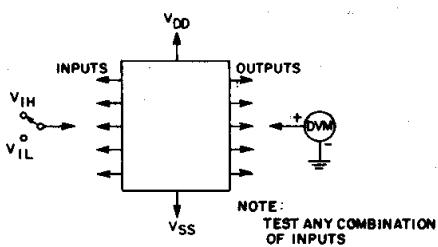


Fig. 16 – Input voltage.

### INTERFACING THE CD4026B AND CD4033B WITH COMMERCIALLY AVAILABLE LIGHT EMITTING DIODE DISPLAYS

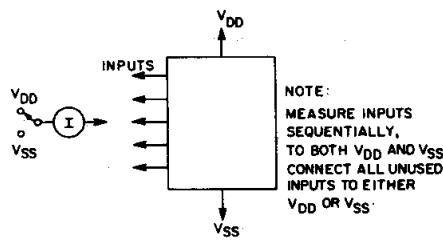
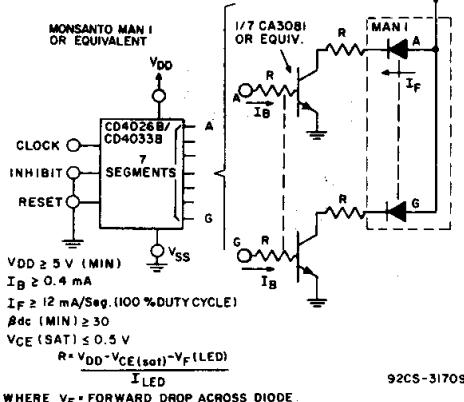
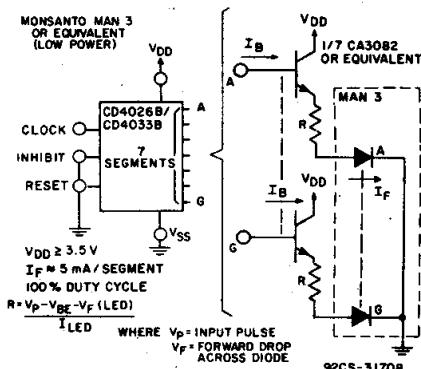
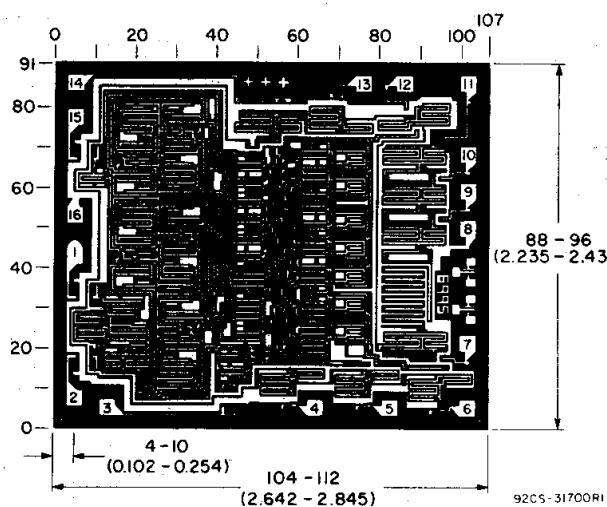
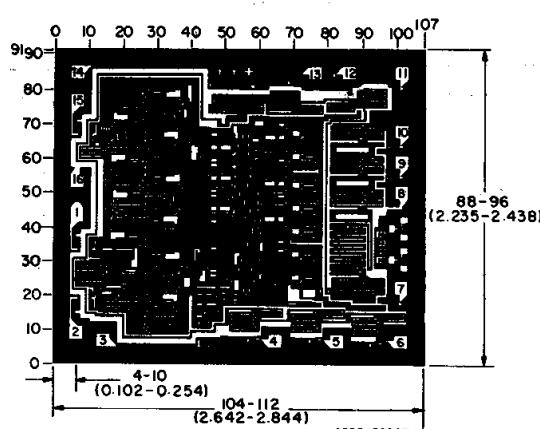


Fig. 17 – Input current.

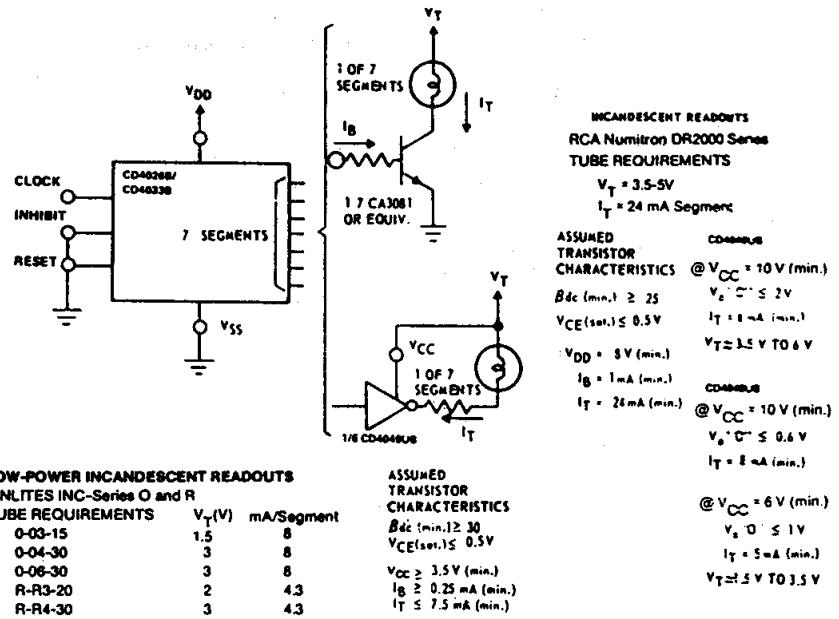


Chip dimensions and pad layout for CD4026B

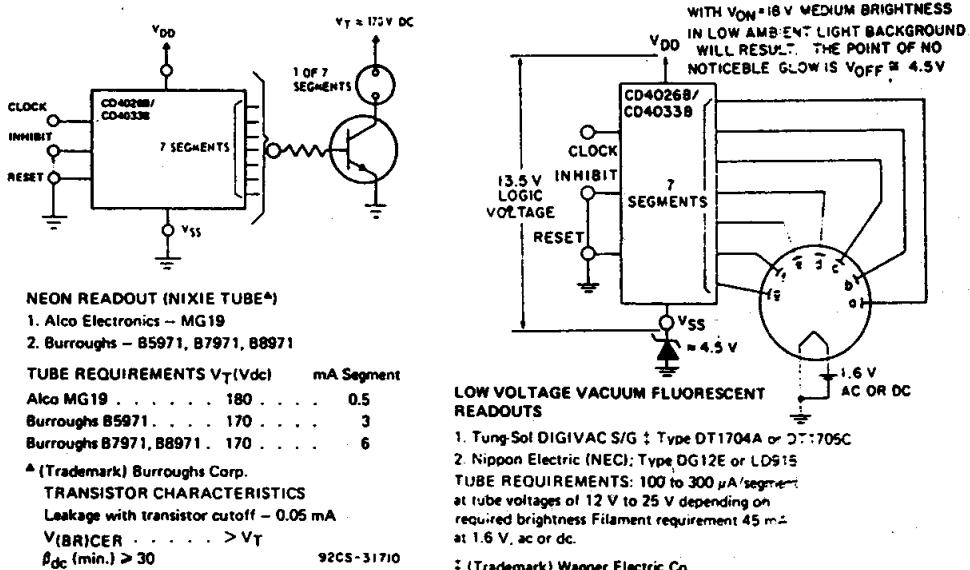
Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).



Chip dimensions and pad layout for CD4033B

**CD4026B, CD4033B Types****INTERFACING THE CD4026B AND CD4033B WITH COMMERCIALLY AVAILABLE 7-SEGMENT DISPLAY DEVICES\***

\* The interfacing buffers shown, while a necessity with the CD4026A and CD4033A, are not required when using the "B" devices; the "B" outputs ( $\approx 10$  times the "A" outputs) can drive most display devices directly especially at voltages above 10 V.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD4026BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4026BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4026BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4033BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4033BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4033BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4033BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4033BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

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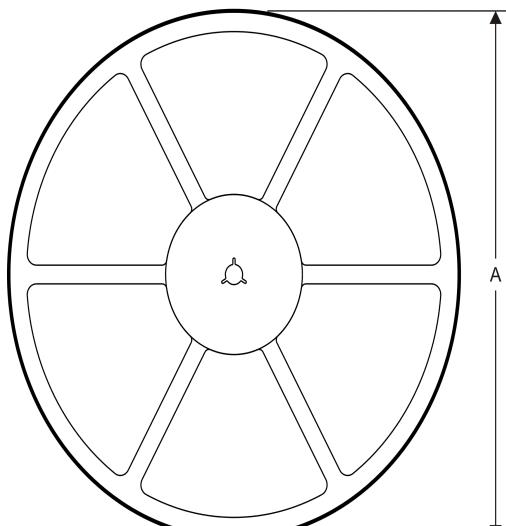
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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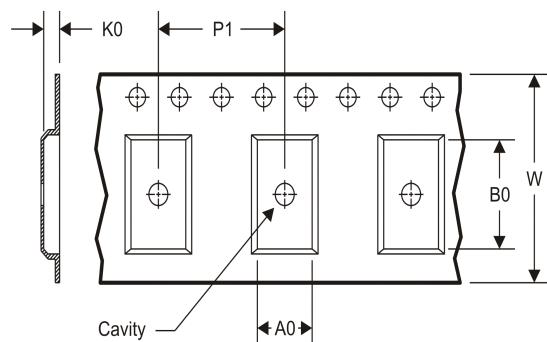
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## TAPE AND REEL INFORMATION

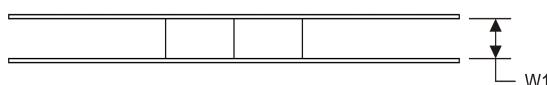
### REEL DIMENSIONS



### TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

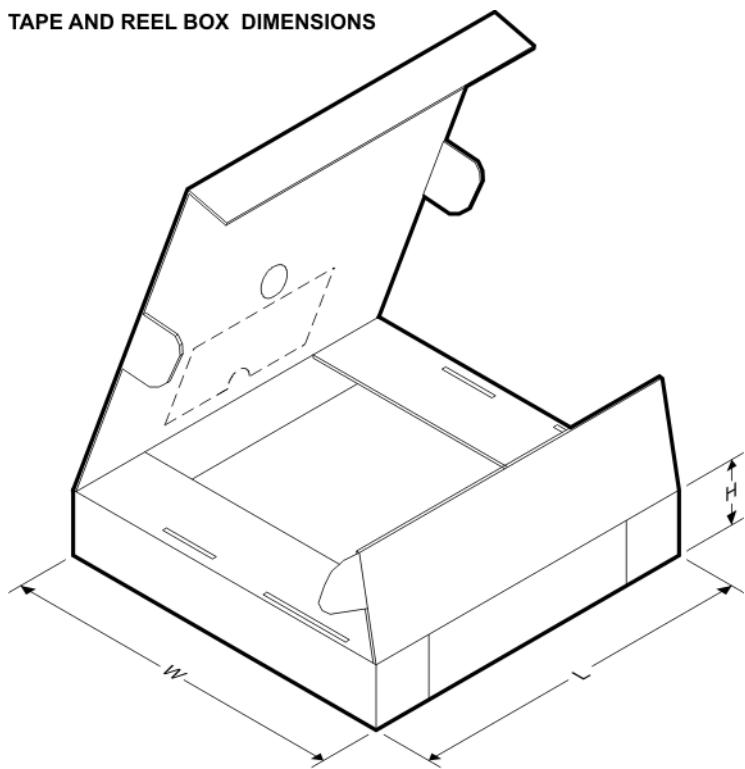


### TAPE AND REEL INFORMATION

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4026BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4026BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



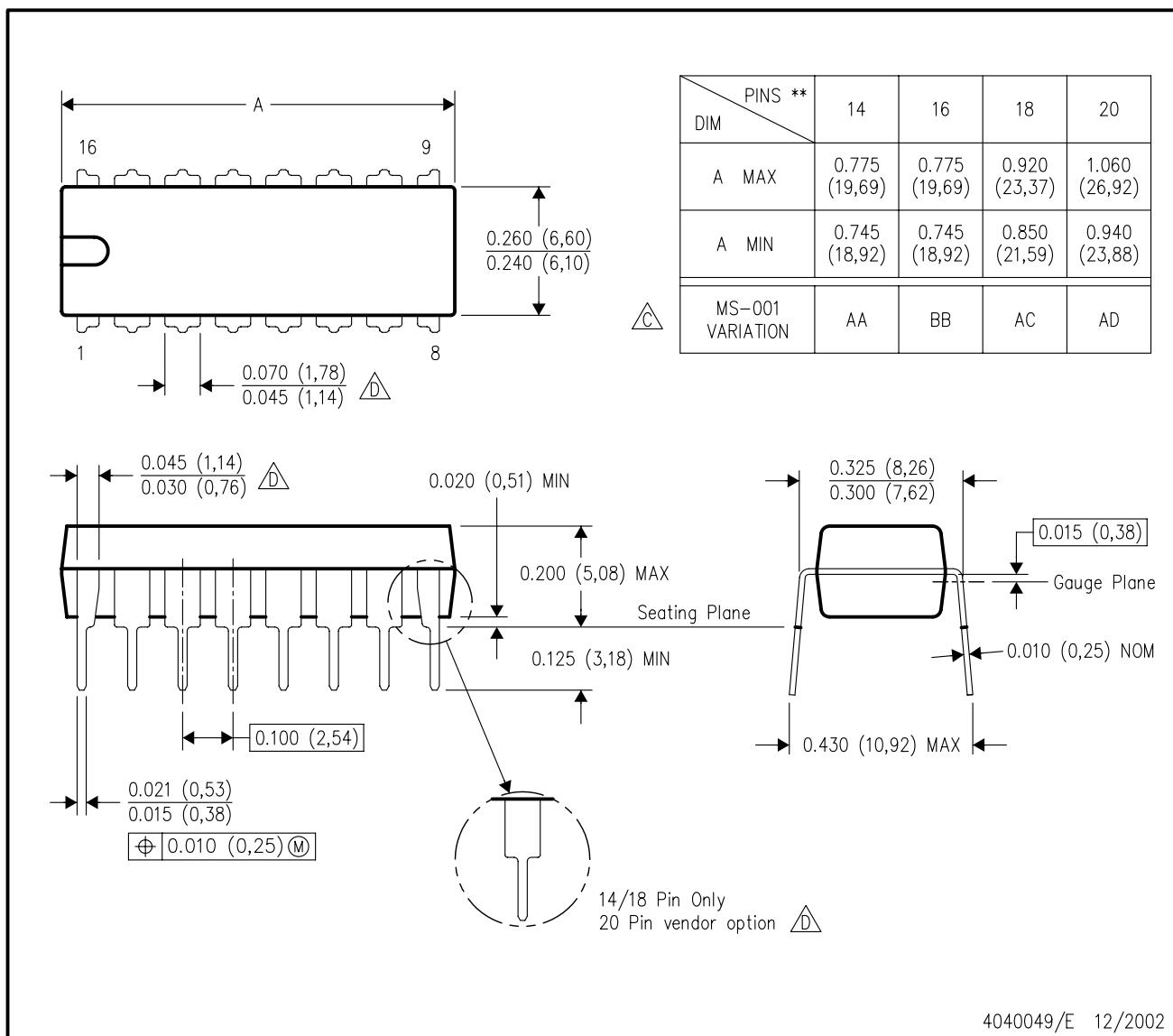
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4026BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4026BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



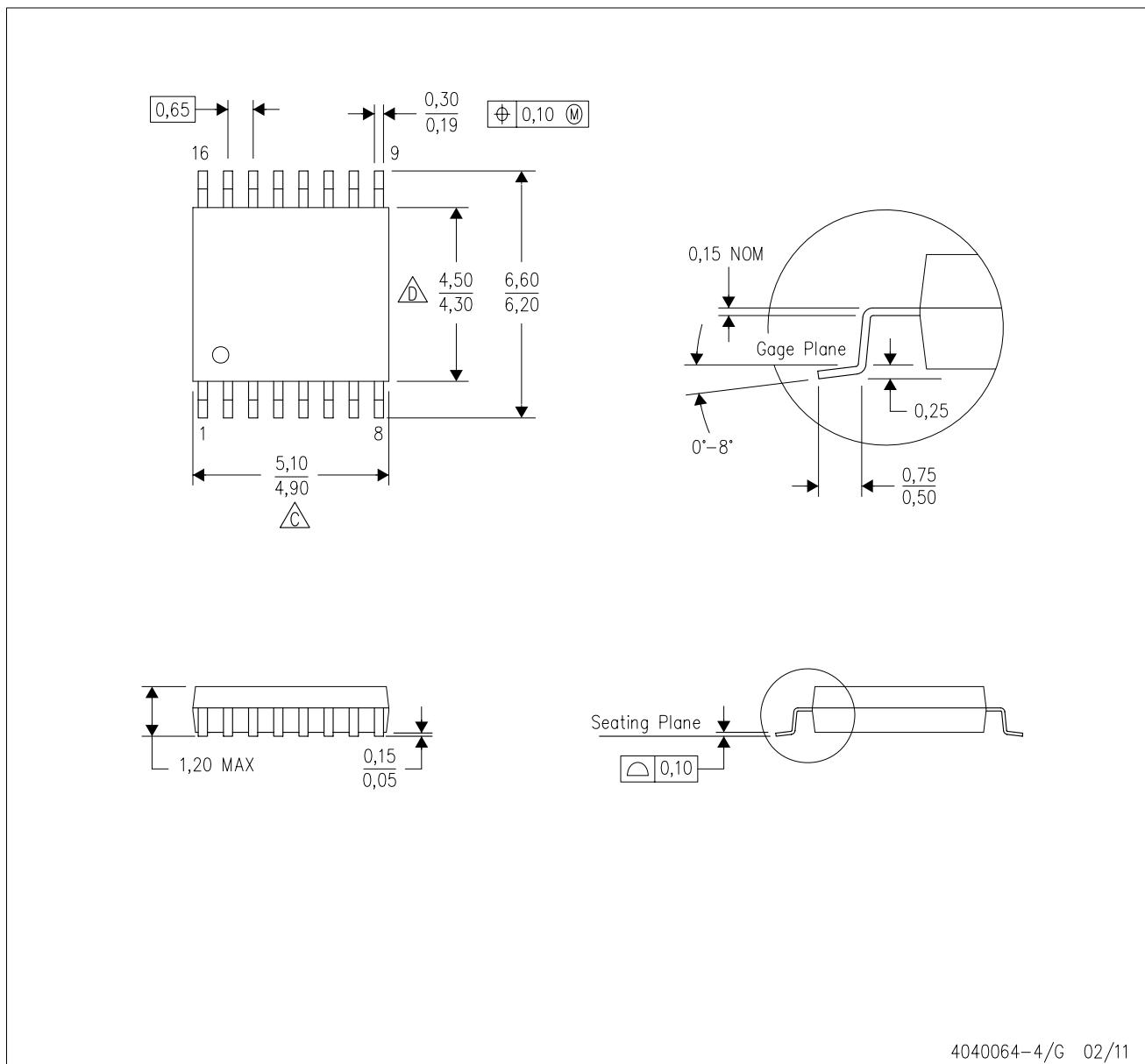
NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040064-4/G 02/11

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

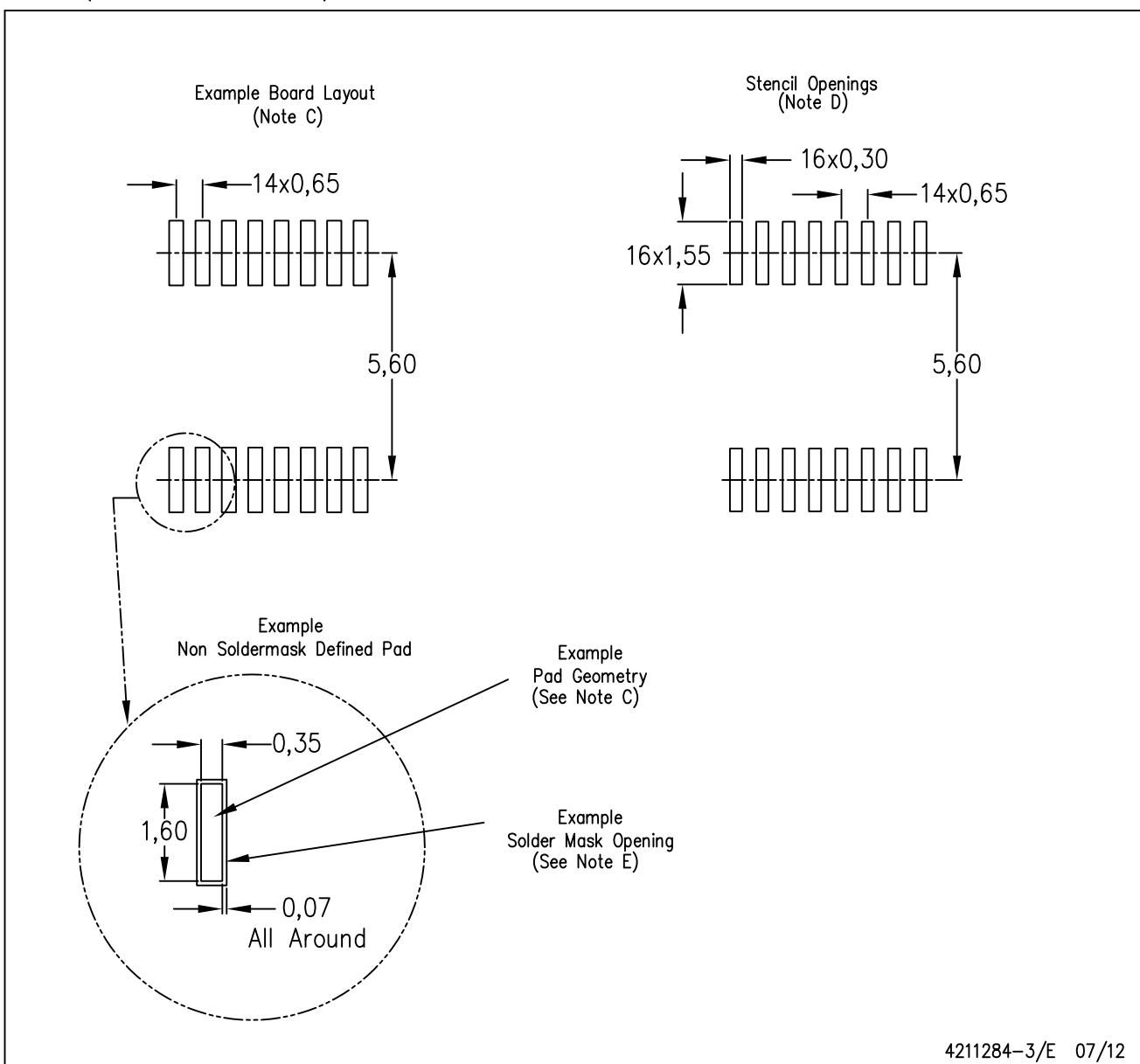
D Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153

## LAND PATTERN DATA

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211284-3/E 07/12

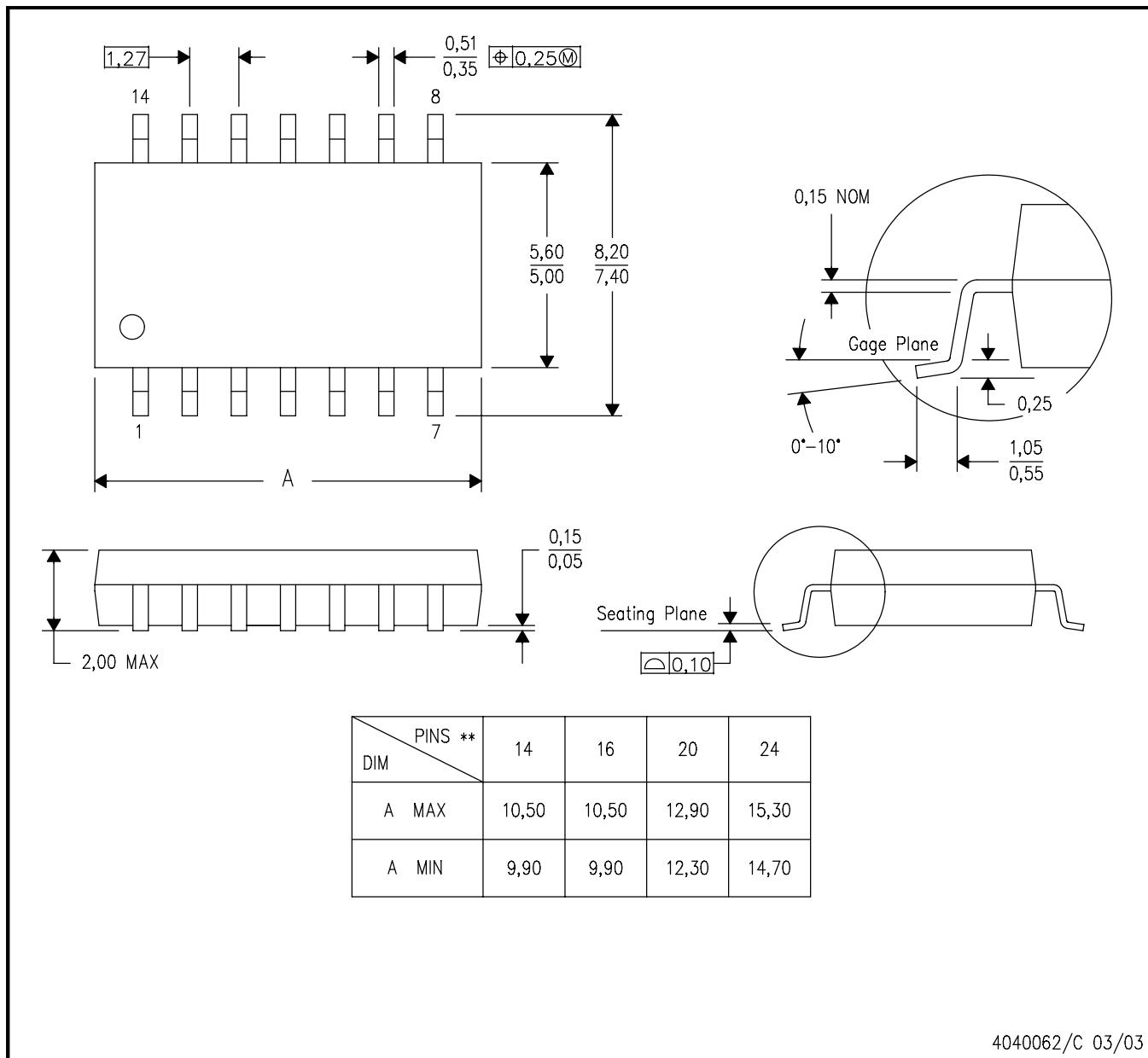
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**14-PINS SHOWN**

**PLASTIC SMALL-OUTLINE PACKAGE**



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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